

SN54AS1000A, SN74AS1000A QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS/DRIVERS

SDAS056B – APRIL 1984 – REVISED JANUARY 1995

- Driver Version of 'AS00
- High Capacitive-Drive Capability
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

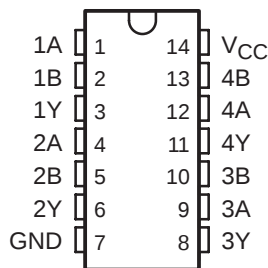
These devices contain four independent 2-input positive-NAND buffers/drivers. They perform the Boolean functions $Y = A \bullet B$ or $Y = \overline{A + B}$ in positive logic.

The SN54AS1000A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74AS1000A is characterized for operation from 0°C to 70°C .

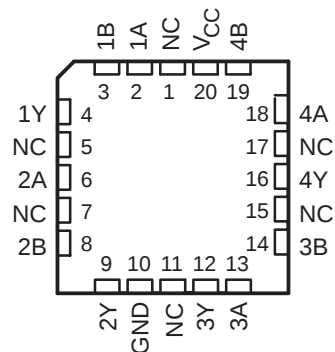
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT Y
A	B	
H	H	L
L	X	H
X	L	H

SN54AS1000A ... J PACKAGE
SN74AS1000A ... D OR N PACKAGE
(TOP VIEW)

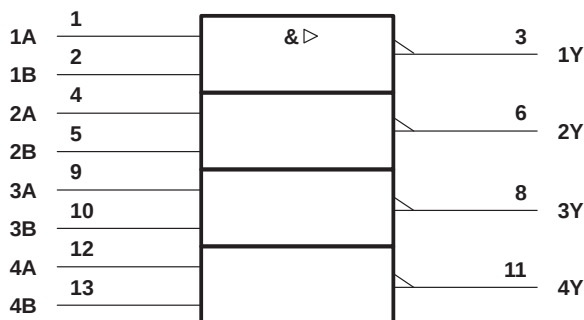


SN54AS1000A ... FK PACKAGE
(TOP VIEW)

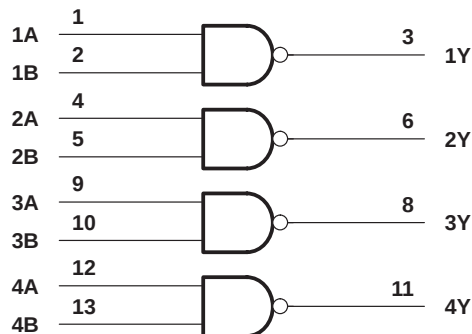


NC – No internal connection

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54AS1000A, SN74AS1000A

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS/DRIVERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54AS1000A	–55°C to 125°C
SN74AS1000A	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions[‡]

		SN54AS1000A			SN74AS1000A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			–40			–48	mA
I_{OL}	Low-level output current			40			48	mA
T_A	Operating free-air temperature	–55		125	0		70	°C

[‡] These high sink- or source-current devices are not recommended for use above 40 MHz.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54AS1000A			SN74AS1000A			UNIT
			MIN	TYP [§]	MAX	MIN	TYP [§]	MAX	
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			–1.2			–1.2	V
V_{OH}	$V_{CC} = 4.5$ V to 5.5 V,	$I_{OH} = -2$ mA	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5$ V	$I_{OH} = -3$ mA	2.4	3.2		2.4	3.2		
		$I_{OH} = -40$ mA	2						
		$I_{OH} = -48$ mA				2			
V_{OL}	$V_{CC} = 4.5$ V	$I_{OL} = 40$ mA	0.25	0.5					V
		$I_{OL} = 48$ mA				0.35	0.5		
I_I	$V_{CC} = 5.5$ V,	$V_I = 7$ V			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			20			20	μA
I_{IL}	$V_{CC} = 5.5$ V,	$V_I = 0.4$ V			–0.5			–0.5	mA
$I_O^{\parallel}$	$V_{CC} = 5.5$ V,	$V_O = 2.25$ V	–30		–200	–50		–200	mA
I_{CCH}	$V_{CC} = 5.5$ V,	$V_I = 0$	2.2	3.5		2.2	3.5		mA
I_{CCL}	$V_{CC} = 5.5$ V,	$V_I = 4.5$ V	12	19		12	19		mA

[§] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

^{||} The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

SN54AS1000A, SN74AS1000A

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS/DRIVERS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54AS1000A		SN74AS1000A		
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	1	5	1	4	ns
t _{PHL}			1	5	1	4	

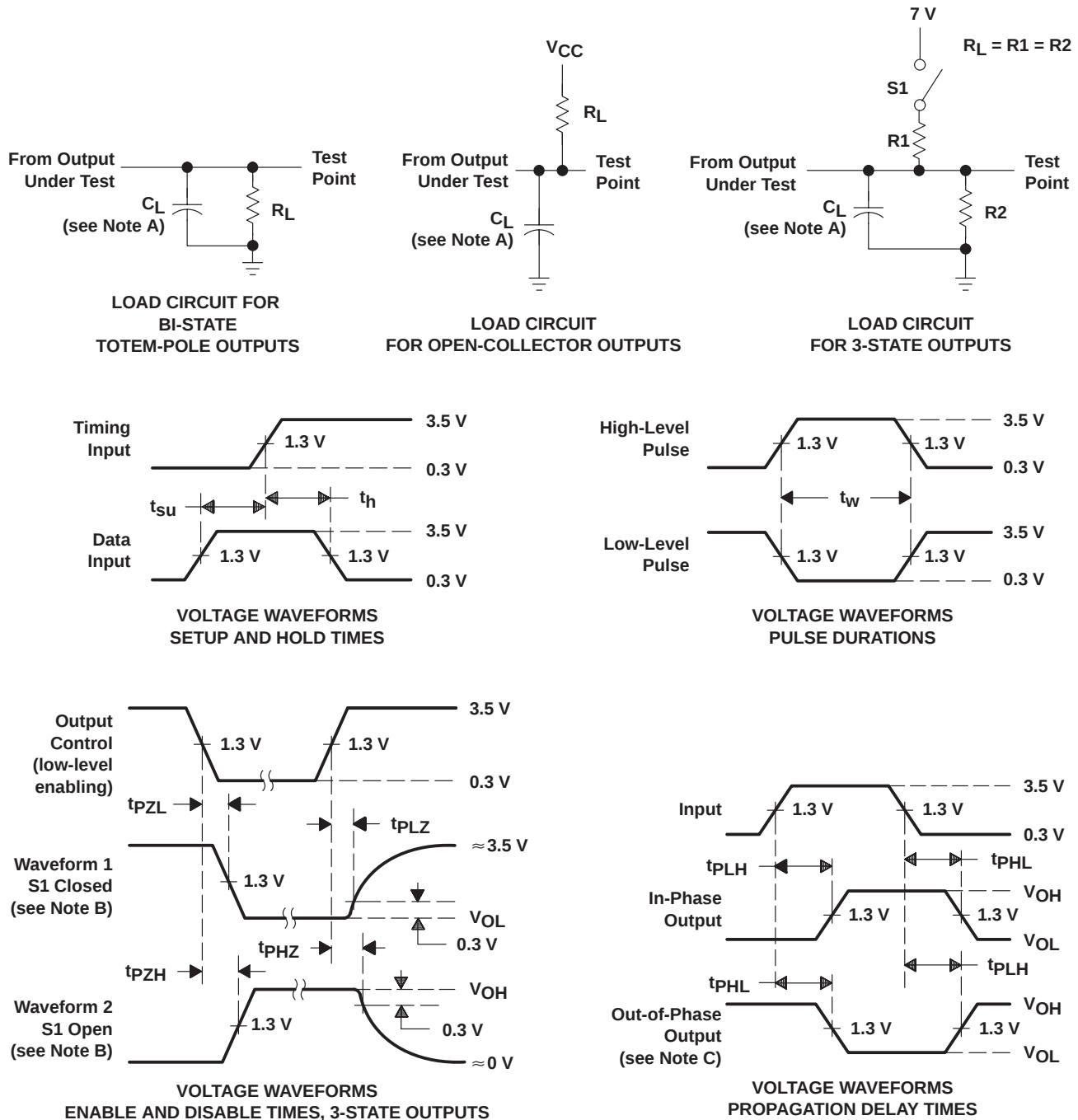
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SN54AS1000A, SN74AS1000A QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS/DRIVERS

SDAS056B – APRIL 1984 – REVISED JANUARY 1995

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9162701M2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9162701M2A SNJ54AS 1000AFK
5962-9162701MCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9162701MC A SNJ54AS1000AJ
SN74AS1000AD	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	0 to 70	AS1000A
SN74AS1000ADR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1000A
SN74AS1000ADR.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1000A
SN74AS1000AN	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74AS1000AN
SN74AS1000AN.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74AS1000AN
SN74AS1000ANSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS1000A
SN74AS1000ANSR.A	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS1000A
SNJ54AS1000AFK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9162701M2A SNJ54AS 1000AFK
SNJ54AS1000AFK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9162701M2A SNJ54AS 1000AFK
SNJ54AS1000AJ	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9162701MC A SNJ54AS1000AJ
SNJ54AS1000AJ.A	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9162701MC A SNJ54AS1000AJ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54AS1000A, SN74AS1000A :

- Catalog : [SN74AS1000A](#)
- Military : [SN54AS1000A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

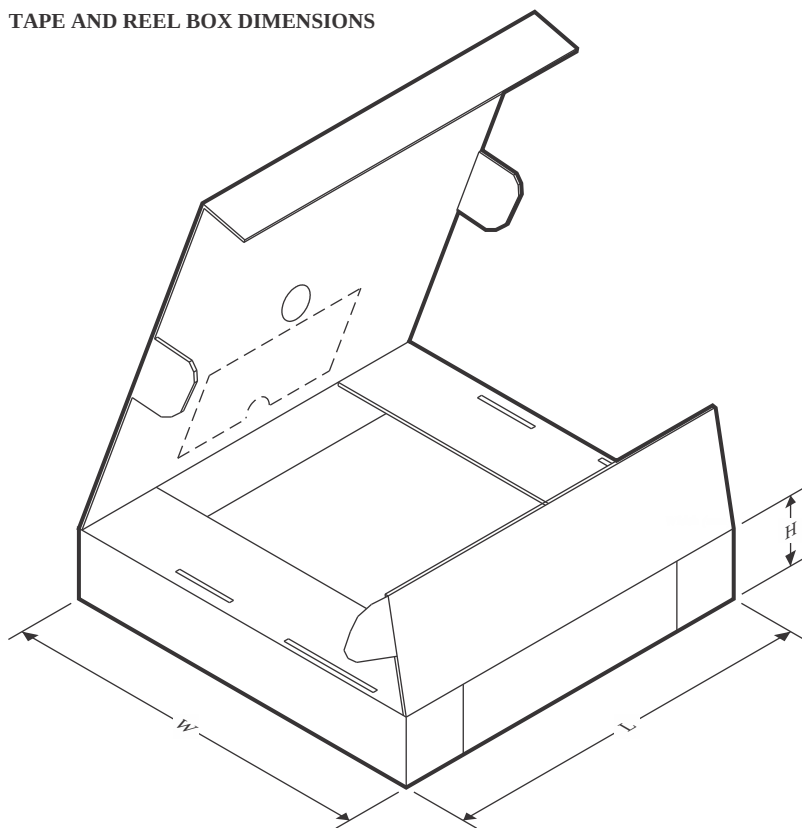
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AS1000ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS1000ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AS1000ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74AS1000ANSR	SOP	NS	14	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9162701M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74AS1000AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1000AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1000AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1000AN.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AS1000AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AS1000AFK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

GENERIC PACKAGE VIEW

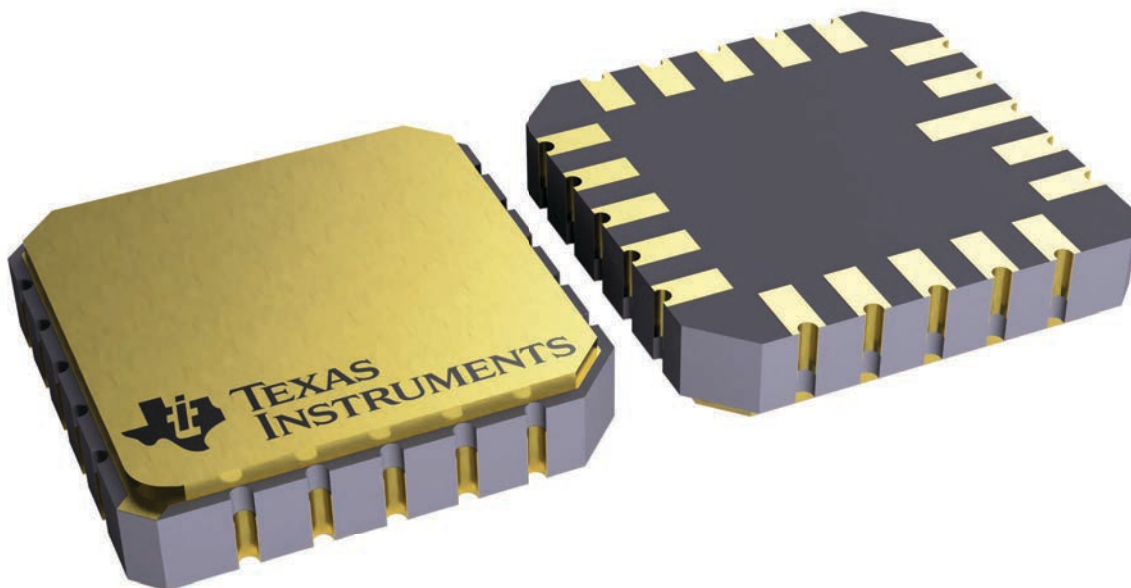
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



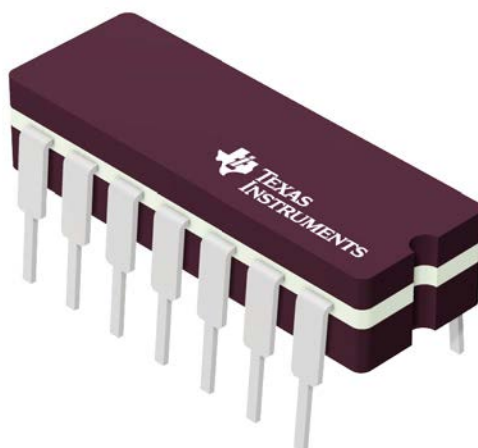
4229370VA\

J 14

GENERIC PACKAGE VIEW

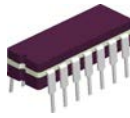
CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE

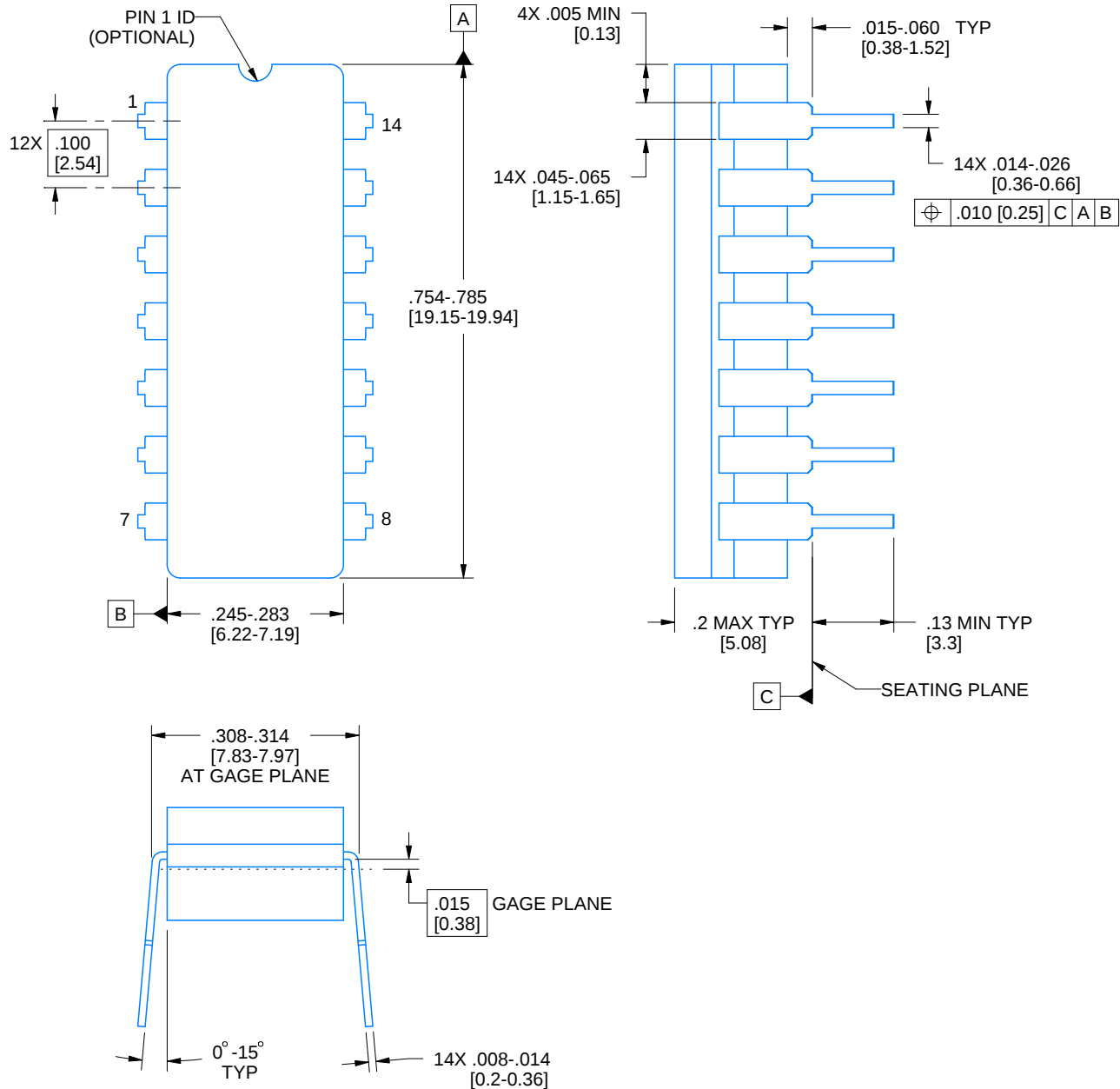


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A**PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



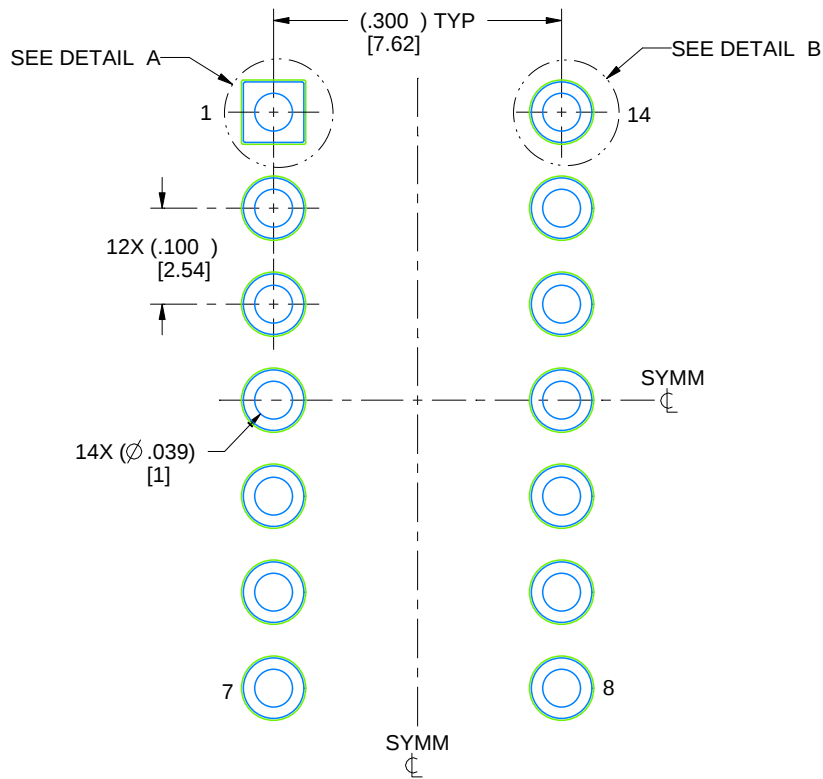
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EXAMPLE BOARD LAYOUT

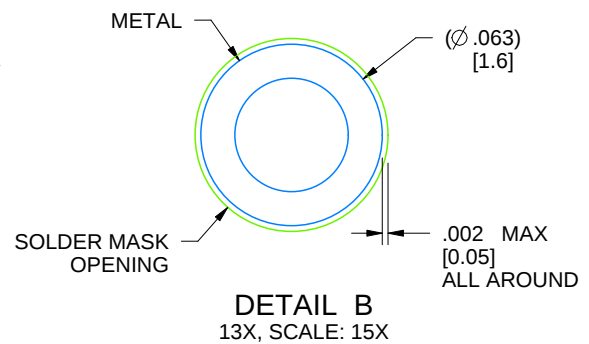
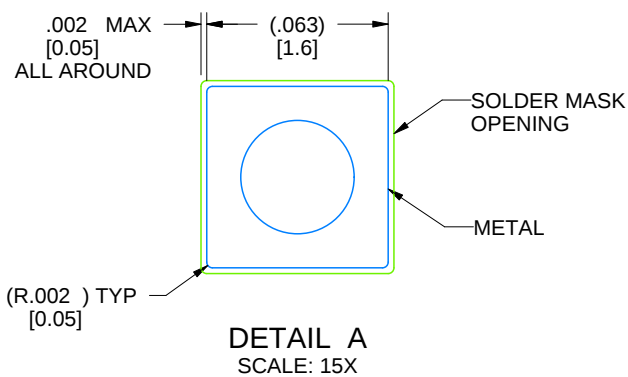
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X

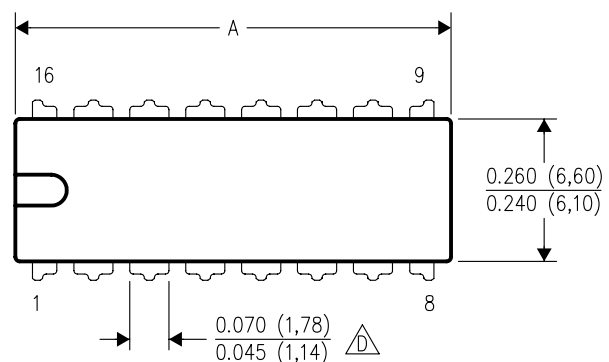


4214771/A 05/2017

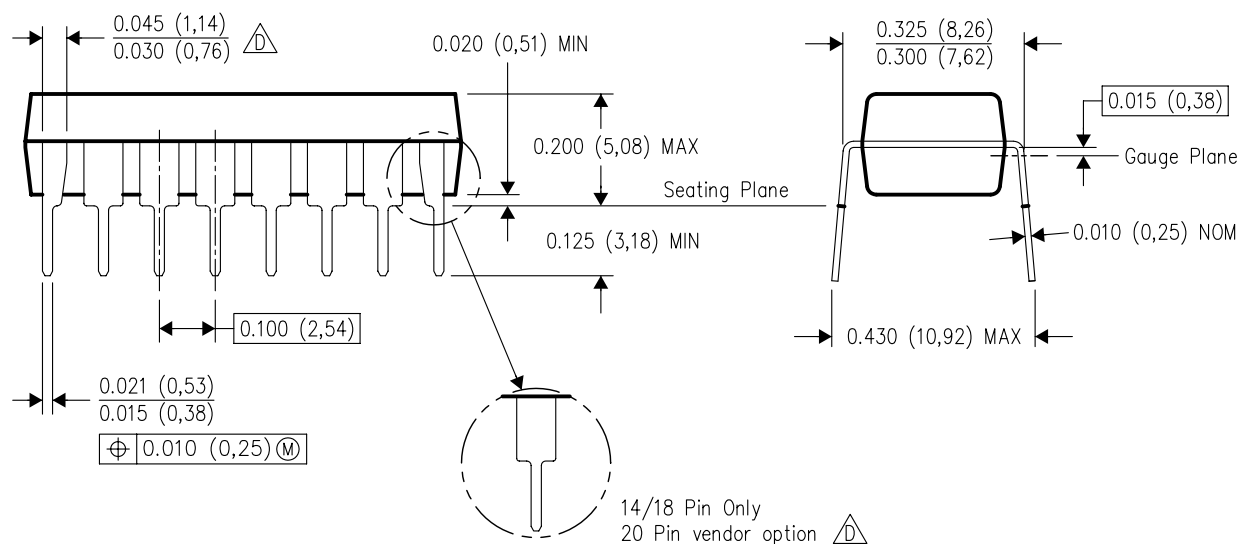
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

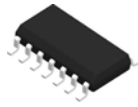


PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

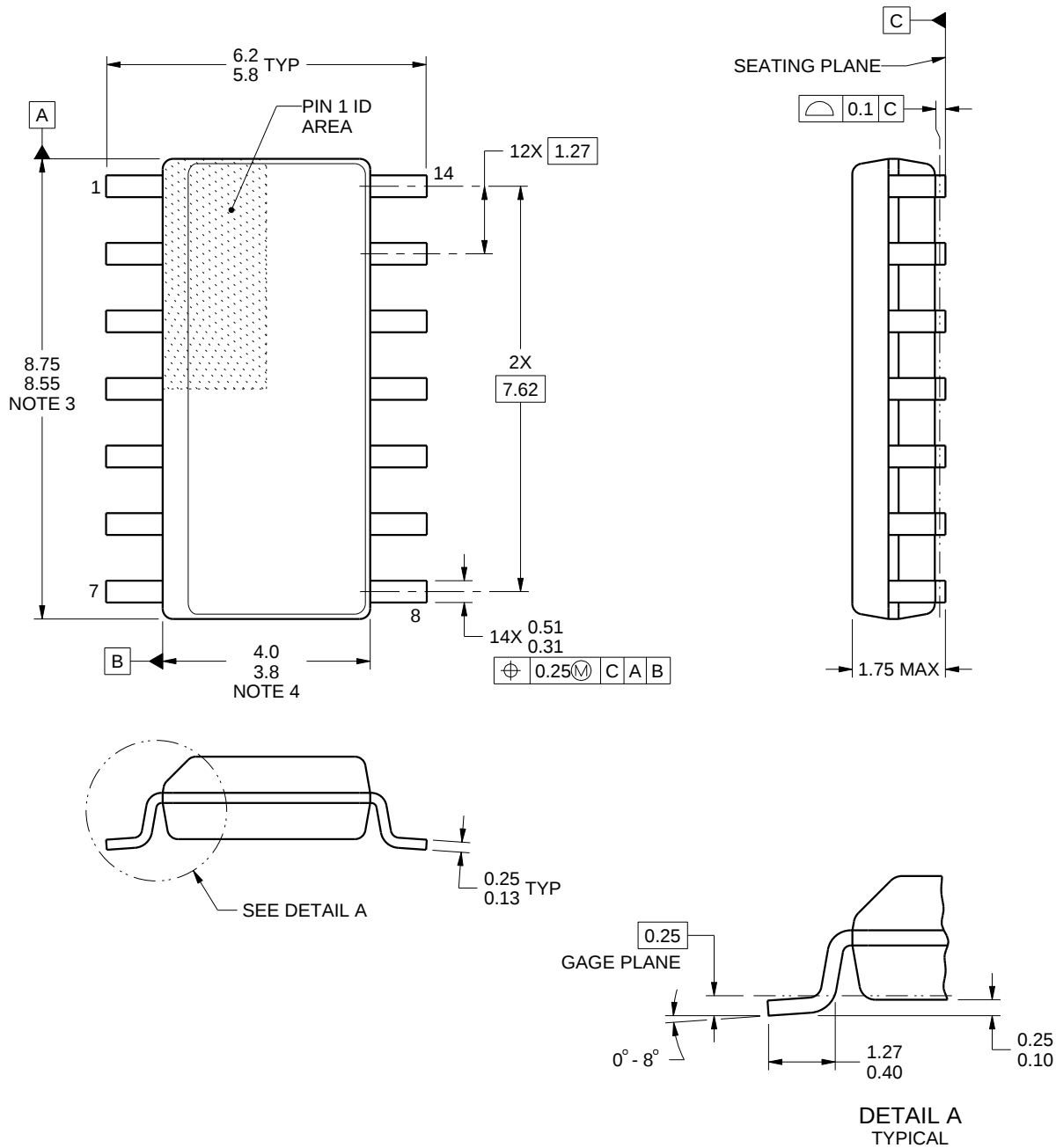


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D0014A**PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

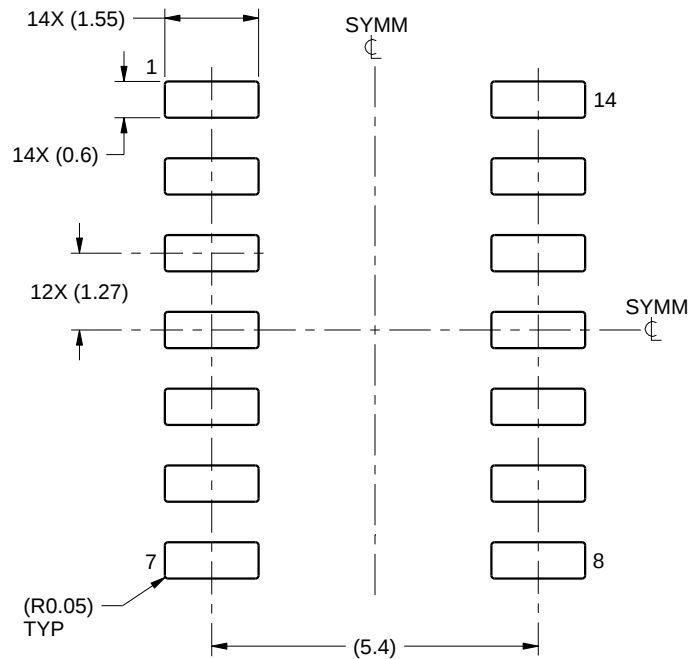
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

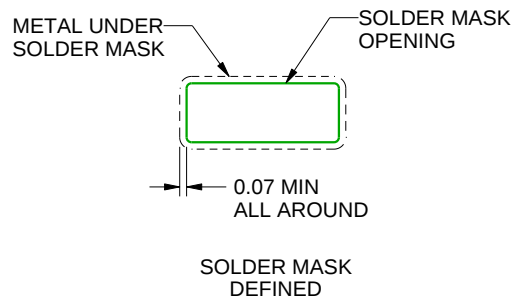
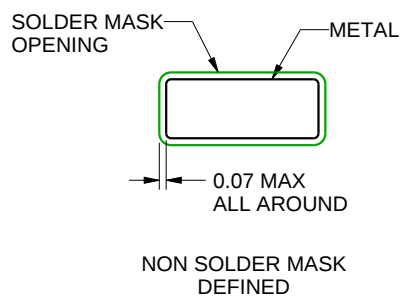
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

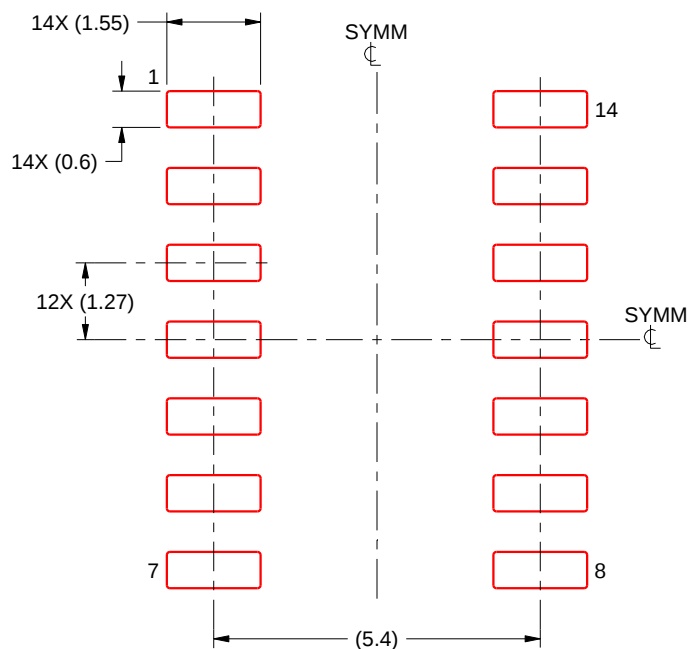
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

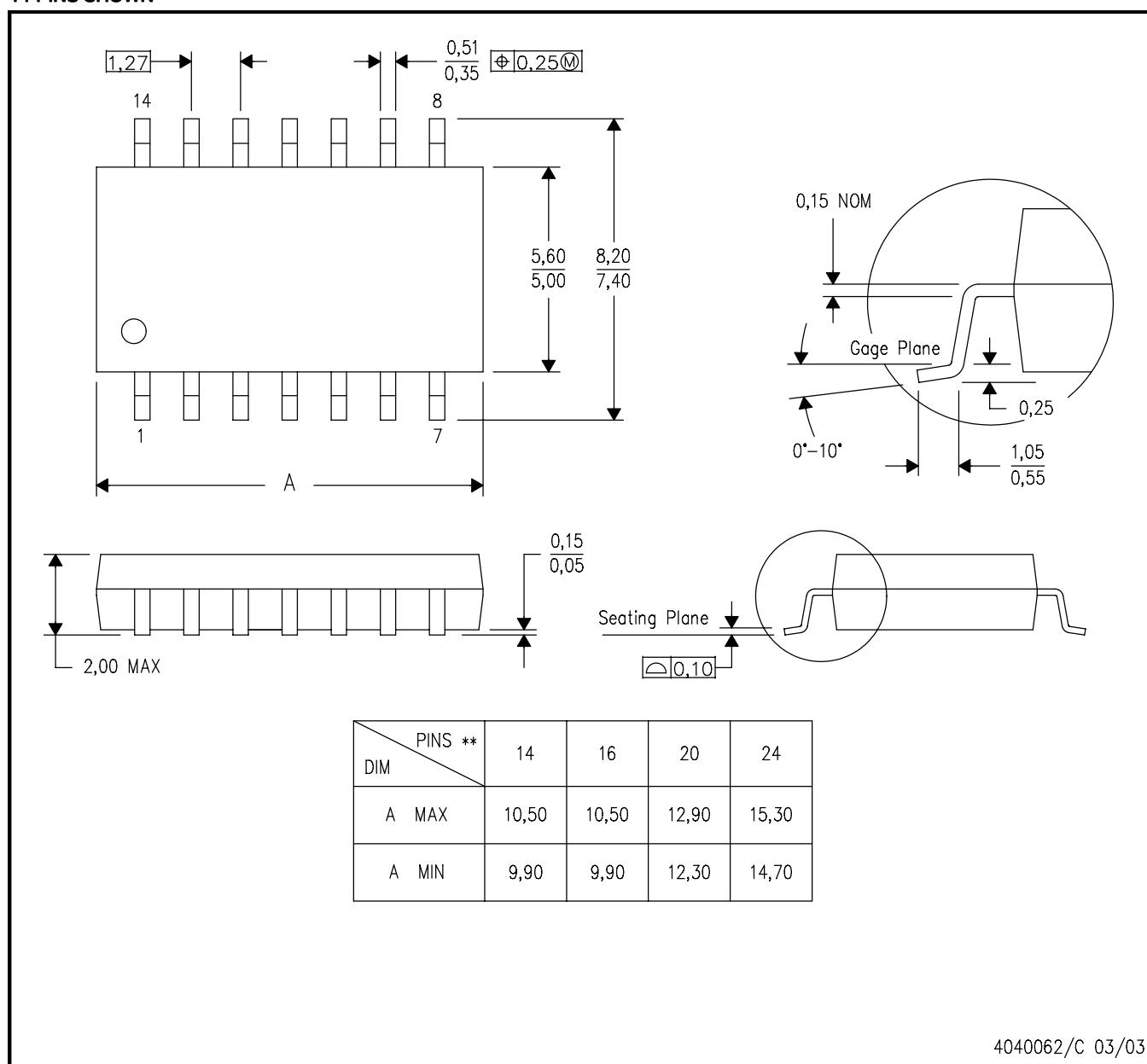
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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